

# GBU15J thru GBU15M

# Single Phase Glass Passivated Silicon Bridge Rectifier

## V<sub>RRM</sub> = 600 V -1000 V I<sub>O</sub> = 15 A

**GBU Package** 

#### Features

- · Plastic package has Underwriters Laboratory
- Flammability Classification 94V-0
- High case dielectric strength of 1500  $V_{\text{RMS}}$
- Glass passivated chip junction
- · Ideal for printed circuit boards
- High surge overload rating
- High temperature soldering guaranteed: 260°C/ 10 seconds, 0.375 (9.5mm) lead length
- Not ESD Sensitive

#### **Mechanical Data**

Case: Molded plastic body over passivated junctions Terminals: Plated leads, solderable per MIL-STD-750 Method 2026. Mounting position: Any

#### Maximum ratings at Tc = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	GBU15J	GBU15K	GBU15M	Unit
Repetitive peak reverse voltage	ge V <sub>RRM</sub>		600	800	1000	V
RMS reverse voltage	V <sub>RMS</sub>		420	560	700	V
DC blocking voltage	V <sub>DC</sub>		600	800	1000	V
Operating temperature	Tj		-55 to 150	-55 to 150	-55 to 150	°C
Storage temperature	T <sub>stg</sub>		-55 to 150	-55 to 150	-55 to 150	°C

#### Electrical characteristics at Tc = 25 °C, unless otherwise specified

Single phase, half sine wave, 60 Hz, resistive or inductive load.

For capacitive load derate current by 20%.

Parameter	Symbol	Conditions	GBU15J	GBU15K	GBU15M	Unit
Maximum average forward rectified current <sup>1,2</sup>	Ι <sub>Ο</sub>	T <sub>c</sub> = 100 °C	15.0	15.0	15.0	А
Peak forward surge current	I <sub>FSM</sub>	t <sub>p</sub> = 8.3 ms, half sine	240	240	240	А
Maximum instantaneous forward voltage drop per leg	V <sub>F</sub>	I <sub>F</sub> = 15 A	1.1	1.1	1.1	V
Maximum DC reverse current at	I <sub>R</sub>	T <sub>a</sub> = 25 °C	5	5	5	μA
rated DC blocking voltage per leg		T <sub>a</sub> = 125 °C	500	500	500	
Typical junction capacitance per leg	C <sub>j</sub>		80	80	80	pF
Typical thermal resistance per leg <sup>1,2</sup>	$R_{\Theta JC}$		2.2	2.2	2.2	°C/W

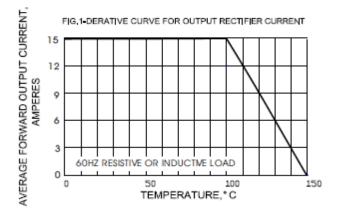
<sup>1</sup> - Device mounted on 100 mm x 100 mm x 1.6 mm Cu plate heatsink

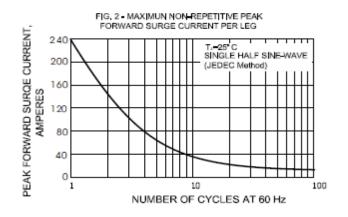
<sup>2</sup> - Recommended mounted position is to bolt down device on a heatsink with silicon thermal compond for maximum heat transfer using #6 screw.

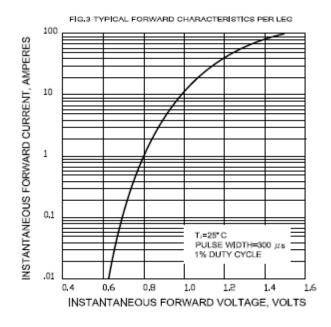
<sup>3</sup> - Measured at 1.0 MHz and applied reverse bias of 4.0 V

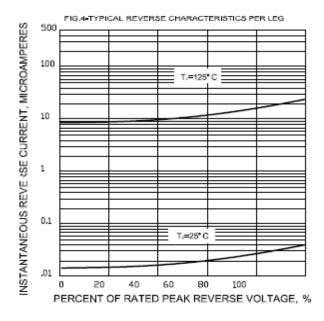


**GBU15J thru GBU15M** 





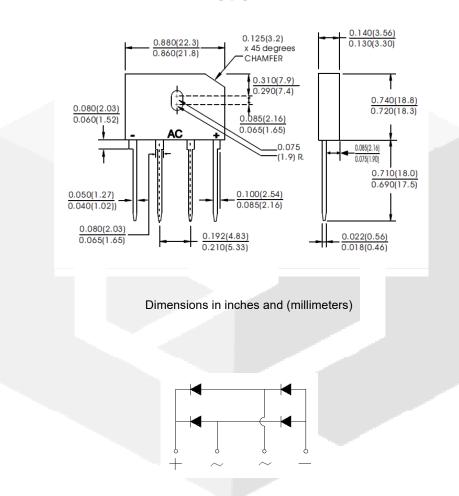






### Package dimensions and terminal configuration

Product is marked with part number and terminal configuration.



GBU